

Enhanced Product

ADM3057E-EP

FEATURES

- 3 kV rms signal and power isolated CAN transceiver**
- isoPower integrated isolated dc-to-dc converter**
- V_{IO} pin for 1.7 V to 5.5 V logic levels**
- ISO 11898-2:2016 compliant (CAN FD)**
- Data rates up to 12 Mbps for CAN FD**
- Low maximum loop propagation delay: 150 ns**
- Extended common-mode range (V_{CANx}): ± 25 V**
- Bus fault protection: ± 40 V on CANH and CANL pins**
- Low power standby support remote wake request**
- Extra isolated signal for control (such as termination switches)**
- Passes EN 55022 Class B by 6 dB**
- Slope control for reduced EMI**

Safety and regulatory approvals

- VDE certificate of conformity, VDE V 0884-10 (pending)**
- $V_{IORM} = 849$ V_{PEAK}**
- UL: 5000 V rms for 1 minute per UL 1577 (pending)**
- CSA Component Acceptance Notice 5A (pending)**
- IEC 60950-1, IEC 61010-1**

Creepage and clearance

7.8 mm minimum with 20-lead SOIC_W

High common-mode transient immunity: >75 kV/ μ s

ENHANCED PRODUCT FEATURES

- Supports defense and aerospace applications (AQEC standard)**
- Military temperature range: -55°C to $+105^{\circ}\text{C}$**
- Controlled manufacturing baseline**
- 1 assembly/test site**
- Product change notification**
- Qualification data available on request**

APPLICATIONS

- CANOpen, DeviceNet, and other CAN bus implementations**
- Industrial automation**
- Military and aerospace (MILA) avionics for sensors, actuators, and engine control**

GENERAL DESCRIPTION

The ADM3057E-EP is a 3 kV rms isolated controller area network (CAN) physical layer transceiver with integrated isolated dc-to-dc converter. The ADM3057E-EP meets flexible data rate (CAN FD) requirements for operation to 5 Mbps and higher and complies with the ISO 11898-2: 2016 standard. The ADM3057E-EP is capable of supporting data rates as high as 12 Mbps.

The device employs Analog Devices, Inc., *iCoupler*® technology to combine a 3-channel isolator, a CAN transceiver, and an Analog Devices *isoPower*® dc-to-dc converter into a single, surface-mount,

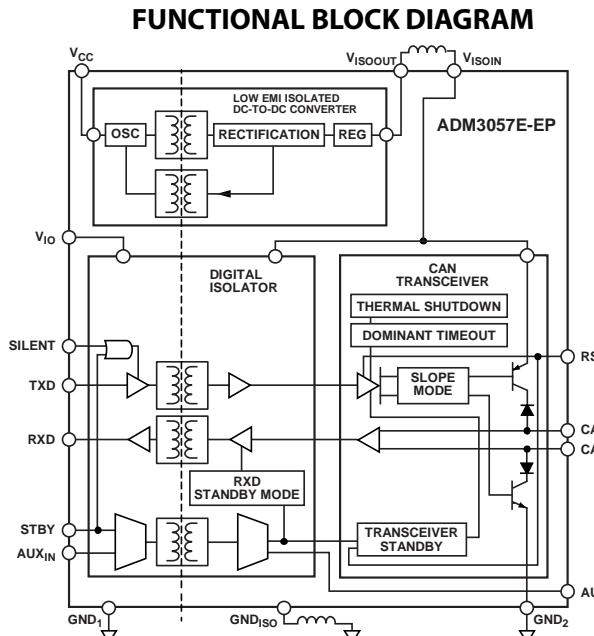


Figure 1.

small outline integrated circuit (SOIC) package. The device is powered by a single 5 V supply, realizing a fully isolated solution for CAN and CAN FD. Radiated emissions from the high frequency switching of the dc-to-dc converters are kept below EN 55022 Class B limits by continuous adjustments to the switching frequency.

The ADM3057E-EP provides complete isolation between the CAN controller and physical layer bus. Safety and regulatory approvals (pending) for 3 kV rms isolation voltage, 10 kV surge test, and 7.8 mm creepage and clearance ensure the ADM3057E-EP meets application reinforced isolation requirements.

Low propagation delays through the isolation support longer bus cables. Slope control mode is available for standard CAN at low data rates. Standby mode minimizes power consumption when the bus is idle or if the node goes offline. Silent mode allows the TXD input to be ignored for listen only mode.

Dominant timeout functionality protects against bus lockup in a fault condition. The current limiting and thermal shutdown features protect against output short circuits. The device is fully specified over a temperature range of -55°C to $+105^{\circ}\text{C}$.

Additional application and technical information can be found in the [ADM3057E](#) data sheet.

Rev. 0

Document Feedback

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REVISION HISTORY

2/2019—Revision 0: Initial Version

SPECIFICATIONS

All voltages are relative to their respective ground. $4.5 \text{ V} \leq V_{CC} \leq 5.5 \text{ V}$, $1.7 \text{ V} \leq V_{IO} \leq 5.5 \text{ V}$, $-55^\circ\text{C} \leq T_A \leq +105^\circ\text{C}$, and STBY low, unless otherwise noted. Typical specifications are at $V_{CC} = V_{IO} = 5 \text{ V}$ and $T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 1.

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
SUPPLY CURRENT						
Logic Side <i>iso</i> Power Current Standby	I _{CC}		13.5	30	mA	STBY high, AUX _{IN} low, load resistance (R_L) = 60 Ω
Recessive State (or Silent)		27	40		mA	TXD and/or SILENT high, R_L = 60 Ω
Dominant State		180	260		mA	Fault condition, R_L = 60 Ω
70% Dominant/30% Recessive						Worst case, R_L = 60 Ω
1 Mbps		138			mA	
5 Mbps		151	200		mA	
12 Mbps		177	220		mA	
Switching Frequency	f _{osc}		180		MHz	Frequency hopping center
Logic Side <i>i</i> Coupler Current	I _{IO}					
Normal Mode		3.6	5		mA	TXD high, low or switching, AUX _{IN} low
Standby Mode		1.2	2		mA	STBY high
DRIVER						
Differential Outputs Recessive State, Normal Mode						See Figure 27 TXD high, R_L and common-mode filter capacitor (C_F) open
CANH, CANL Voltage	V _{CANL} , V _{CANH}	2.0	3.0		V	
Differential Output Voltage	V _{OD}	-500	+50		mV	
Dominant State, Normal Mode						TXD and SILENT low, C_F open
CANH Voltage	V _{CANH}	2.75	4.5		V	50 Ω ≤ R_L ≤ 65 Ω
CANL Voltage	V _{CANL}	0.5	2.0		V	50 Ω ≤ R_L ≤ 65 Ω
Differential Output Voltage	V _{OD}	1.5	3.0		V	50 Ω ≤ R_L ≤ 65 Ω
		1.4	3.3		V	45 Ω ≤ R_L ≤ 70 Ω
		1.5	5.0		V	R_L = 2240 Ω
Standby Mode						STBY high, R_L and C_F open
CANH, CANL Voltage	V _{CANL} , V _{CANH}	-0.1	+0.1		V	
Differential Output Voltage	V _{OD}	-200	+200		mV	
Output Symmetry ($V_{ISOIN} - V_{CANH} - V_{CANL}$)	V _{SYM}	-0.55	+0.55		V	R_L = 60 Ω, C_F = 4.7 nF, RS low
Short-Circuit Current	I _{SC}					R_L open
Absolute						
CANH			115		mA	$V_{CANH} = -3 \text{ V}$
CANL			115		mA	$V_{CANL} = 18 \text{ V}$
Steady State						
CANH			115		mA	$V_{CANH} = -24 \text{ V}$
CANL			115		mA	$V_{CANL} = 24 \text{ V}$
Logic Inputs (TXD, SILENT, STBY, AUX _{IN})						
Input Voltage						
High	V _{IH}	0.65 × V _{IO}			V	
Low	V _{IL}		0.35 × V _{IO}		V	
Complementary Metal-Oxide Semiconductor (CMOS) Logic Input Currents	I _{IH} , I _{IL}		10		μA	Input high or low

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
RECEIVER						
Differential Inputs						
Differential Input Voltage Range	V _{ID}					See Figure 28, C _{RXD} open, −25 V < V _{CANL} , V _{CANH} < +25 V
Recessive		−1.0	+0.5		V	
Dominant		−1.0	+0.4		V	STBY high
Differential		0.9	5.0		V	
Input Voltage Hysteresis	V _{HYS}		150		mV	
Unpowered Input Leakage Current	I _{IN(OFF)}		10		μA	V _{CANH} , V _{CANL} = 5 V, V _{CC} = 0 V
Input Resistance						
CANH, CANL	R _{INH} , R _{INL}	6	25		kΩ	
Differential	R _{DIFF}	20	100		kΩ	
Matching	m _R	−0.03	+0.03		Ω/Ω	m _R = 2 × (R _{INH} − R _{INL})/(R _{INH} + R _{INL})
Input Capacitance						
CANH, CANL	C _{INH} , C _{INL}		35		pF	
Differential	C _{DIFF}		12		pF	
Logic Outputs (RXD, AUX _{OUT})						
Output Voltage						
Low	V _{OL}		0.2	0.4	V	Output current (I _{OUT}) = 2 mA
High	V _{OH}					
RXD		V _{IO} − 0.2			V	I _{OUT} = −2 mA
AUX _{OUT}		+2.4			V	I _{OUT} = −2 mA
Short-Circuit Current						
RXD	I _{OS}	7	85		mA	Output voltage (V _{OUT}) = GND ₁ or V _{IO}
COMMON-MODE TRANSIENT IMMUNITY ¹						
Input High, Recessive	CM _H	75	100		kV/μs	Common-mode voltage (V _{CM}) ≥ 1 kV, transient magnitude ≥ 800 V V _{IN} = V _{IO} (AUX _{IN} , TXD) or CANH/CANL recessive
Input Low, Dominant	CM _L	75	100		kV/μs	V _{IN} = 0 V (AUX _{IN} , TXD) or CANH/CANL dominant
SLOPE CONTROL						
Input Voltage for Standby Mode	V _{STB}	4.0			V	
Current for Slope Control Mode	I _{SLOPE}		−240		μA	RS voltage (V _{RS}) = 0 V
Slope Control Mode Voltage	V _{SLOPE}	2.1			V	RS current (I _{RS}) = 10 μA
Input Voltage for High Speed Mode	V _{HS}		1		V	

¹ |CM_H| is the maximum common-mode voltage slew rate that can be sustained while maintaining AUX_{OUT} ≥ 2.4 V, CANH/CANL recessive, or RXD ≥ V_{IO} − 0.2 V. |CM_L| is the maximum common-mode voltage slew rate that can be sustained while maintaining AUX_{OUT} ≤ 0.4 V, CANH/CANL dominant, or RXD ≤ 0.4 V. The common-mode voltage slew rates apply to both rising and falling common-mode voltage edges.

TIMING SPECIFICATIONS

All voltages are relative to their respective ground. $4.5 \text{ V} \leq V_{CC} \leq 5.5 \text{ V}$, $1.7 \text{ V} \leq V_{IO} \leq 5.5 \text{ V}$, $-55^\circ\text{C} \leq T_A \leq +105^\circ\text{C}$, and STBY low, unless otherwise noted. Typical specifications are at $V_{CC} = V_{IO} = 5 \text{ V}$ and $T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 2.

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
DRIVER						SILENT low, bit time on the TXD pin as transmitted by the CAN controller ($t_{BIT_TXD} = 200 \text{ ns}$, see Figure 2 and Figure 29, slope resistance ($R_{SLOPE} = 0 \Omega$, $R_L = 60 \Omega$, load capacitance ($C_L = 100 \text{ pF}$))
Maximum Data Rate		12			Mbps	
Propagation Delay from TXD to Bus (Recessive to Dominant)	t_{TXD_DOM}		35	60	ns	
Propagation Delay from TXD to Bus (Dominant to Recessive)	t_{TXD_REC}		46	70	ns	
Transmit Dominant Timeout	t_{DT}	1175		4000	μs	TXD low, see Figure 5
RECEIVER						SILENT low, see Figure 2 and Figure 29, $R_L = 60 \Omega$, $C_L = 100 \text{ pF}$, RXD capacitance ($C_{RXD} = 15 \text{ pF}$)
Falling Edge Loop Propagation Delay (TXD to RXD)	t_{LOOP_FALL}					
Full Speed Mode			150		ns	$R_{SLOPE} = 0 \Omega$, $t_{BIT_TXD} = 200 \text{ ns}$
Slope Control Mode			300		ns	$R_{SLOPE} = 47 \text{ k}\Omega$, $t_{BIT_TXD} = 1 \mu\text{s}$
Rising Edge Loop Propagation Delay (TXD to RXD)	t_{LOOP_RISE}					
Full Speed Mode			150		ns	$R_{SLOPE} = 0 \Omega$, $t_{BIT_TXD} = 200 \text{ ns}$
Slope Control Mode			300		ns	$R_{SLOPE} = 47 \text{ k}\Omega$, $t_{BIT_TXD} = 1 \mu\text{s}$
Loop Delay Symmetry (Minimum Recessive Bit Width)	t_{BIT_RXD}					
2 Mbps		450	550		ns	$t_{BIT_TXD} = 500 \text{ ns}$
5 Mbps		160	220		ns	$t_{BIT_TXD} = 200 \text{ ns}$
8 Mbps		85	140		ns	$t_{BIT_TXD} = 125 \text{ ns}$
12 Mbps		50	91.6		ns	$t_{BIT_TXD} = 83.3 \text{ ns}$
CANH, CANL SLEW RATE	$ SR $		7		V/μs	SILENT low, see Figure 29, $R_L = 60 \Omega$, $C_L = 100 \text{ pF}$, $R_{SLOPE} = 47 \text{ k}\Omega$
STANDBY MODE						
Minimum Pulse Width Detected (Receiver Filter Time)	t_{FILTER}	1	5		μs	STBY high, see Figure 4
Wake-Up Pattern Detection Reset Time	t_{WUPR}	1175	4000		μs	STBY high, see Figure 4
Normal Mode to Standby Mode Time	t_{STBY_ON}		25		μs	
Standby Mode to Normal Mode Time	t_{STBY_OFF}		25		μs	Time until RXD valid
AUXILIARY SIGNAL						
Maximum Switching Rate	f_{AUX}	20			kHz	
AUX _{IN} to AUX _{OUT} Propagation Delay	t_{AUX}		25		μs	
SILENT MODE						
Normal Mode to Silent Mode Time	t_{SILENT_ON}		40	100	ns	TXD low, $R_{SLOPE} = 0 \Omega$, see Figure 3
Silent Mode to Normal Mode Time	t_{SILENT_OFF}		50	100	ns	TXD low, $R_{SLOPE} = 0 \Omega$, see Figure 3

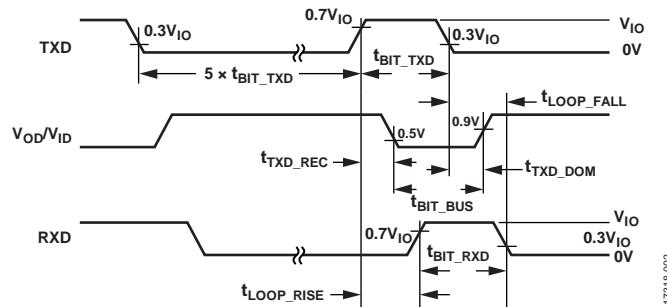
Timing Diagrams

Figure 2. Transceiver Timing Diagram

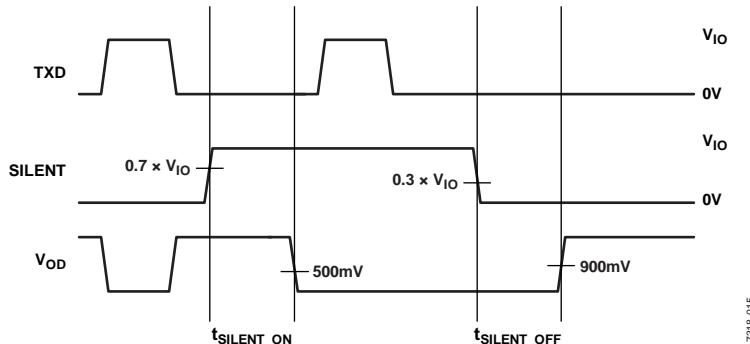


Figure 3. Silent Mode Timing Diagram

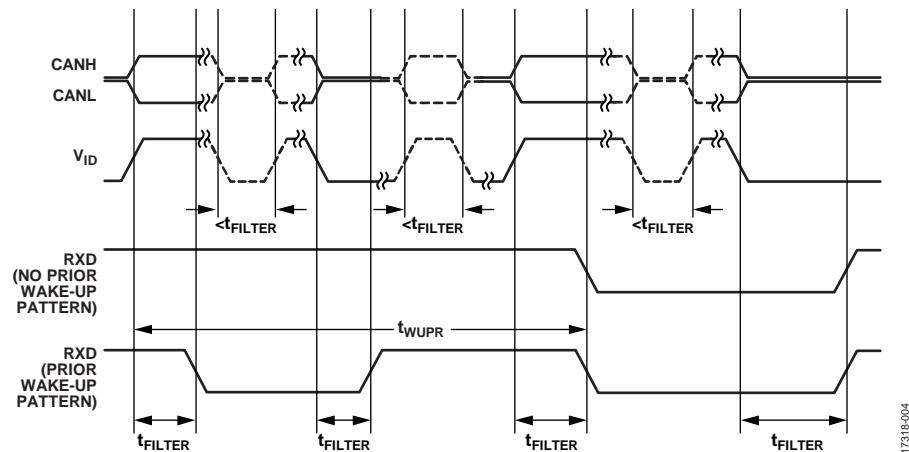


Figure 4. Wake-Up Pattern Detection and Filtered RXD in Standby Mode Timing Diagram

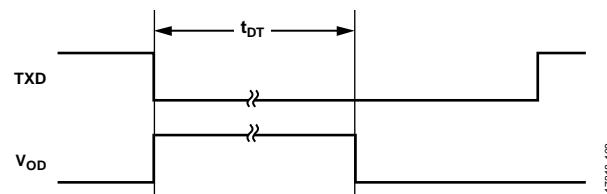


Figure 5. Dominant Timeout

INSULATION AND SAFETY RELATED SPECIFICATIONS

For additional information, see www.analog.com/icouplersafety.

Table 3.

Parameter	Symbol	Value	Unit	Test Conditions/Comments
Rated Dielectric Insulation Voltage		3000	V rms	1-minute duration
Minimum External Air Gap (Clearance)	L (I01)	7.8	mm min	Measured from input terminals to output terminals, shortest distance through air
Minimum External Tracking (Creepage)	L (I02)	7.8	mm min	Measured from input terminals to output terminals, shortest distance path along body
Minimum Clearance in the Plane of the Printed Circuit Board (PCB Clearance)	L (PCB)	7.8	mm min	Measured from input terminals to output terminals, shortest distance through air, line of sight, in the PCB mounting plane
Minimum Internal Gap (Internal Clearance)		21	μm min	Insulation distance through insulation
Tracking Resistance (Comparative Tracking Index)	CTI	>600	V	IEC 60112
Material Group		I		Material Group (IEC 60664-1)

PACKAGE CHARACTERISTICS**Table 4.**

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
Resistance (Input to Output) ¹	R _{I-O}		10 ¹³		Ω	
Capacitance (Input to Output) ¹	C _{I-O}		3.7		pF	f = 1 MHz
Input Capacitance ²	C _I		4.0		pF	

¹ The device is considered a 2-terminal device: Pin 1 through Pin 10 are shorted together, and Pin 11 through Pin 20 are shorted together.

² Input capacitance is from any input data pin to ground.

REGULATORY INFORMATION

See Table 9 for details regarding maximum working voltages for specific cross isolation waveforms and insulation levels. The ADM3057E-EP is approved or pending approval by the organizations listed in Table 5.

Table 5.

UL (Pending) ¹	CSA (Pending)	VDE (Pending) ²	CQC (Pending)
Recognized Under UL 1577 Component Recognition Program Single Protection, 3000 V rms Isolation Voltage	Approved under CSA Component Acceptance Notice 5A CSA 60950-1-07+A1+A2 and IEC 60950-1, second edition, +A1+A2 Basic insulation at 780 V rms (1103 V _{PEAK}) Reinforced insulation at 390 V rms (552 V _{PEAK}) IEC 60601-1 Edition 3.1: Basic insulation (1 MOPP), 490 V rms (693 V _{PEAK}) Reinforced insulation (2 MOPP), 250 V rms (353 V _{PEAK}) CSA 61010-1-12 and IEC 61010-1 third edition Basic insulation at 300 V rms mains, 780 V secondary (1103 V _{PEAK}) Reinforced insulation at 300 V rms mains, 390 V secondary (552 V _{PEAK}) File 205078	DIN V VDE V 0884-10 (VDE V 0884-10):2006-12 Reinforced insulation 849 V _{PEAK} , surge isolation voltage (V _{IOTM}) = 6000 V _{PEAK} File 2471900-4880-0001	Certified under CQC11-471543-2012 GB4943.1-2011: basic insulation at 780 V rms (1103 V _{PEAK}) Reinforced insulation at 390 V rms (552 V _{PEAK}) File (pending)
File E214100			

¹ In accordance with UL 1577, each ADM3057E-EP is proof tested by applying an insulation test voltage ≥ 3600 V rms for 1 sec.

² In accordance with DIN V VDE V 0884-10, each ADM3057E-EP is proof tested by applying an insulation test voltage ≥ 1592 V_{PEAK} for 1 sec (partial discharge detection limit = 5 pC). The * marking branded on the component designates DIN V VDE V 0884-10 approval.

DIN V VDE V 0884-10 (VDE V 0884-10) INSULATION CHARACTERISTICS

These isolators are suitable for reinforced electrical isolation only within the safety limit data. The protective circuits ensure the maintenance of the safety data. The asterisk (*) marking on packages denotes DIN V VDE V 0884-10 approval.

Table 6. VDE Characteristics

Description	Test Conditions/Comments	Symbol	Characteristic	Unit
Installation Classification per DIN VDE 0110			I to IV	
For Rated Mains Voltage ≤ 150 V rms			I to IV	
For Rated Mains Voltage ≤ 300 V rms			I to III	
For Rated Mains Voltage ≤ 400 V rms			55/105/21	
Climatic Classification			2	
Pollution Degree per DIN VDE 0110, Table 1		V_{IORM}	849	V_{PEAK}
Maximum Working Insulation Voltage		$V_{pd(m)}$	1592	V_{PEAK}
Input to Output Test Voltage, Method B1	$V_{IORM} \times 1.875 = V_{PR}$, 100% production test, $t_m = 1$ sec, partial discharge < 5 pC			
Input to Output Test Voltage, Method A				
After Environmental Tests Subgroup 1	$V_{IORM} \times 1.5 = V_{pd(m)}$, $t_{ini} = 60$ sec, $t_m = 10$ sec, partial discharge < 5 pC	$V_{pd(m)}$	1273	V_{PEAK}
After Input or Safety Test Subgroup 2 and Subgroup 3	$V_{IORM} \times 1.2 = V_{pd(m)}$, $t_{ini} = 60$ sec, $t_m = 10$ sec, partial discharge < 5 pC	$V_{pd(m)}$	1018	V_{PEAK}
Highest Allowable Overvoltage	Transient overvoltage, $t_{TR} = 10$ sec	V_{IOTM}	6000	V_{PEAK}
Surge Isolation Voltage Reinforced	$V_{IOSM(TEST)} = 10$ kV, 1.2 μ s rise time, 50 μ s, 50% fall time	V_{IOSM}	6000	V_{PEAK}
Safety Limiting Values	Maximum value allowed in the event of a failure (see Figure 6)			
Case Temperature		T_s	150	$^{\circ}\text{C}$
Total Power Dissipation at 25°C		P_s	2.35	W
Insulation Resistance at T_s	$V_{IO} = 500$ V	R_s	$>10^9$	Ω

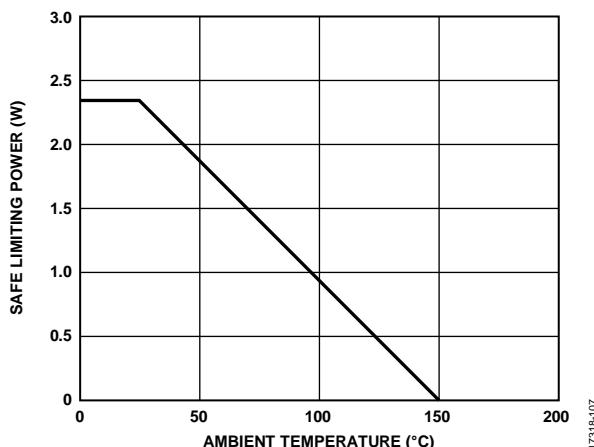


Figure 6. Thermal Derating Curve, Dependence of Safety Limiting Values with Ambient Temperature per DIN V VDE V 0884-10

ABSOLUTE MAXIMUM RATINGS

Pin voltages with respect to GND_x are on the same side, unless otherwise noted.

Table 7.

Parameter	Rating
V _{CC}	-0.5 V to +6 V
V _{IO}	-0.5 V to +6 V
Logic Side Input/Output: TXD, RXD, AUX _{IN} , SILENT, STBY	-0.5 V to V _{IO} + 0.5 V
CANH, CANL	-40 V to +40 V
AUX _{OUT} , RS	-0.5 V to V _{ISOIN} + 0.5 V
Operating Temperature Range	-55°C to +105°C
Storage Temperature Range	-65°C to +150°C
Junction Temperature (T _J Maximum)	150°C
Power Dissipation	(T _J maximum - T _A) / θ _{JA}
Electrostatic Discharge (ESD) IEC 61000-4-2, CANH/CANL	
Across Isolation Barrier to GND ₁	±8 kV
Contact Discharge to GND ₂	±8 kV
Air Discharge to GND ₂	±15 kV
Human Body Model (HBM), All Pins, 1.5 kΩ, 100 pF	4 kV
Moisture Sensitivity Level (MSL)	MSL3

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

Thermal performance is directly linked to PCB design and operating environment. Careful attention to PCB thermal design is required.

The thermal resistance value specified in Table 8 is simulated based on JEDEC specifications (unless specified otherwise) and must be used in compliance with JESD51-12.

Table 8. Thermal Resistance

Package Type	θ _{JA}	Unit
RW-20 ¹	53	°C/W

¹ The θ_{JA} value is based on simulations of a device mounted on a JEDEC standard, 4-layer board with fine width traces and still air. See the [ADM3057E](#) data sheet for thermal model definitions.

ESD CAUTION



ESD (electrostatic discharge) sensitive device.
Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

Table 9. Maximum Continuous Working Voltage¹

Parameter	Rating	Unit	Constraint
AC Voltage			
Bipolar Waveform			
Basic Insulation	566	V _{PEAK}	Lifetime limited by insulation lifetime per VDE-0884-11
Reinforced Insulation	467	V _{PEAK}	Lifetime limited by insulation lifetime per VDE-0884-11
Unipolar Waveform			
Basic Insulation	1131	V _{PEAK}	Lifetime limited by insulation lifetime per VDE-0884-11
Reinforced Insulation	933	V _{PEAK}	Lifetime limited by insulation lifetime per VDE-0884-11
DC Voltage			
Basic Insulation	1560	V _{PEAK}	Lifetime limited by package creepage per IEC 60664-1
Reinforced Insulation	780	V _{PEAK}	Lifetime limited by package creepage per IEC 60664-1

¹ Maximum continuous working voltage refers to the continuous voltage magnitude imposed across the isolation barrier. See the [ADM3057E](#) data sheet for more details.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

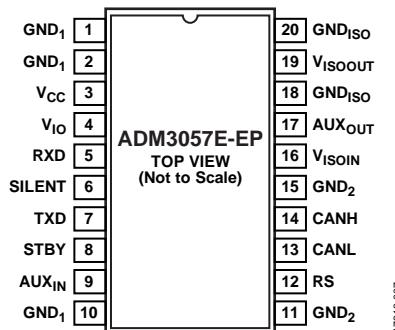


Figure 7. Pin Configuration

Table 10. Pin Function Descriptions

Pin No.	Mnemonic	Description
1, 2, 10	GND ₁	Ground, Logic Side.
3	V _{CC}	<i>isoPower</i> Power Supply, 4.5 V to 5.5 V. This pin requires 0.1 µF and 10 µF decoupling capacitors.
4	V _{IO}	<i>iCoupler</i> Power Supply, 1.7 V to 5.5 V. This pin requires 0.01 µF and 0.1 µF decoupling capacitors.
5	RXD	Receiver Output Data.
6	SILENT	Silent Mode Select with Input High. Bring this input low or leave the pin unconnected (internal pull-down) for normal mode.
7	TXD	Driver Input Data. This pin has a weak internal pull-up resistor to V _{IO} .
8	STBY	Standby Mode Select with Input High. Bring this input low or leave the pin unconnected (internal pull-down) for normal mode.
9	AUX _{IN}	Auxiliary Channel Input. This pin sets the AUX _{OUT} output.
11, 15	GND ₂	Ground, Bus Side.
12	RS	Slope Control Pin. Short this pin to ground for full speed operation or use a weak pull-down resistor (for example, 47 kΩ) for slope control mode. An input high signal places the CAN transceiver in standby mode.
13	CANL	CAN Low Input/Output.
14	CANH	CAN High Input/Output.
16	V _{ISOIN}	Isolated Power Supply Input for the CAN Transceiver Bus Side Digital Isolator. This pin requires 0.01 µF and 0.1 µF decoupling capacitors.
17	AUX _{OUT}	Isolated Auxiliary Channel Output. The state of AUX _{OUT} is latched when STBY is high. By default, AUX _{OUT} is low at startup or when V _{IO} is unpowered.
18, 20	GND _{ISO}	Ground for the Isolated DC-to-DC Converter. Connect these pins together through one ferrite bead to PCB ground (bus side).
19	V _{ISOOUT}	Isolated Power Supply Output. This pin requires 0.22 µF and 10 µF capacitors to GND _{ISO} . Connect this pin through a ferrite bead and short the PCB trace to V _{ISOIN} for operation.

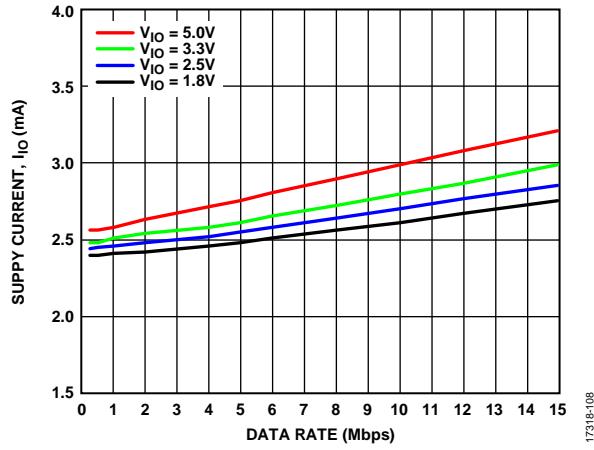
OPERATIONAL TRUTH TABLE

Table 11. Truth Table

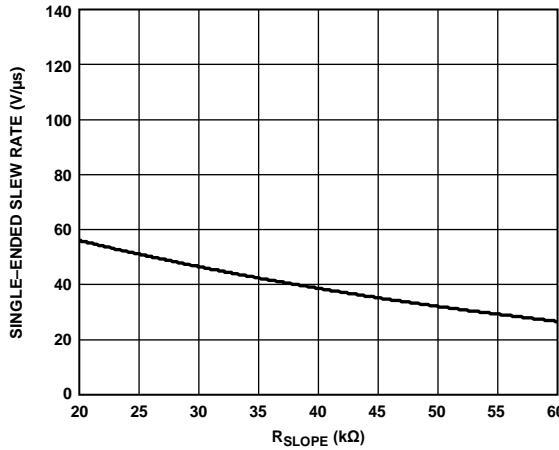
Power		Inputs ^{1,2}					Mode	Outputs ²		Input/Output
V _{cc}	V _{io}	TXD	SILENT	STBY	AUX _{IN}	RS		RXD ³	AUX _{OUT}	CANH/CANL
On	On	Low	Low	Low	Low	Low/pull-down	Normal/slope mode	Low	Low	Dominant ⁴
On	On	Low	Low	Low	High	Low/pull-down	Normal/slope mode	Low	High	Dominant ⁴
On	On	High	Low	Low	Low	Low/pull-down	Normal/slope mode	High/per bus	Low	Recessive/set by bus
On	On	High	Low	Low	High	Low/pull-down	Normal/slope mode	High/per bus	High	Recessive/set by bus
On	On	X	High	Low	Low	X	Listen only	High/per bus	Low	Recessive/set by bus
On	On	X	High	Low	High	X	Listen only	High/per bus	High	Recessive/set by bus
On	On	X	X	High	X	X	Standby	High/WUP/filtered	Last state	Bias to GND ₂ /set by bus
On	On	X	X	X	Low	Pull-up	Standby ⁵	High/WUP/filtered	Low	Bias to GND ₂ /set by bus
On	On	X	X	X	High	Pull-up	Standby ⁵	High/WUP/filtered	High	Bias to GND ₂ /set by bus
On	Off	Z	Z	Z	Z	Low/pull-down	Normal/slope mode	Z	Low	Recessive/set by bus
Off	On	X	X	X	X	X	Transceiver off	High	Z	High impedance/set by bus
Off	Off	Z	Z	Z	Z	Z	Transceiver off	Z	Z	High impedance/set by bus

¹ X means irrelevant.² Z means high impedance within one diode drop of ground.³ WUP means remote wake-up pattern.⁴ Limited by t_{DT}.⁵ RS can only set the transceiver to standby mode. RS does not control the digital isolator.

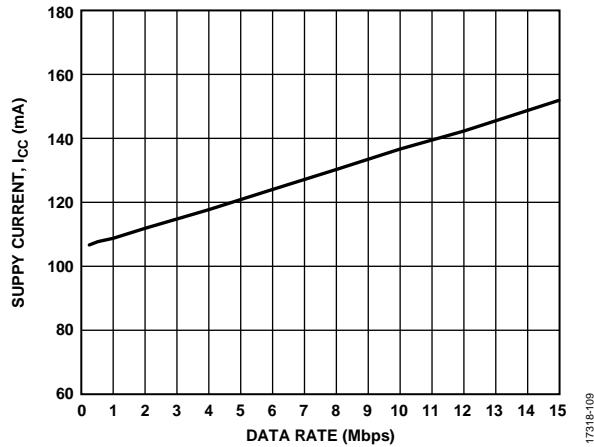
TYPICAL PERFORMANCE CHARACTERISTICS

Figure 8. Supply Current, I_{IO} vs. Data Rate

17318-108

Figure 11. Single-Ended Slew Rate vs. R_{SLOPE}

17318-11

Figure 9. Supply Current, I_{CC} vs. Data Rate

17318-109

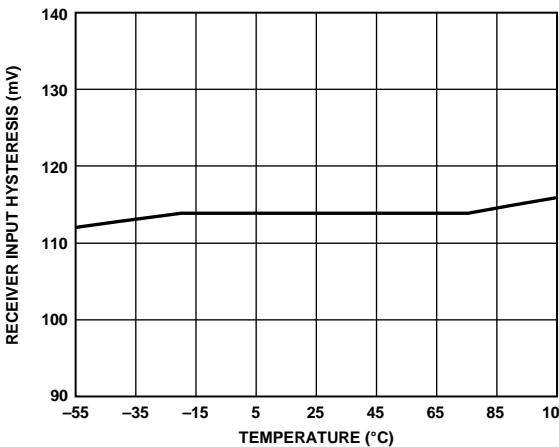
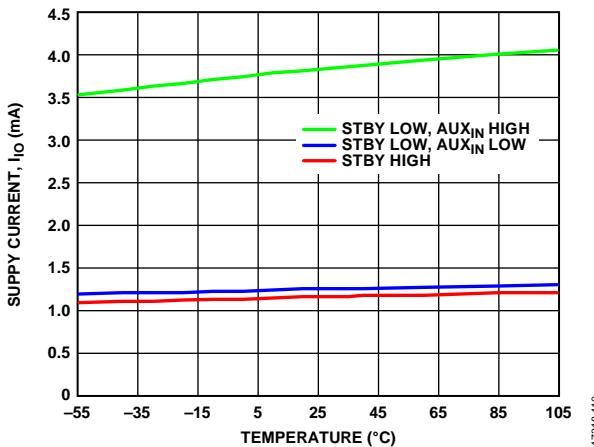
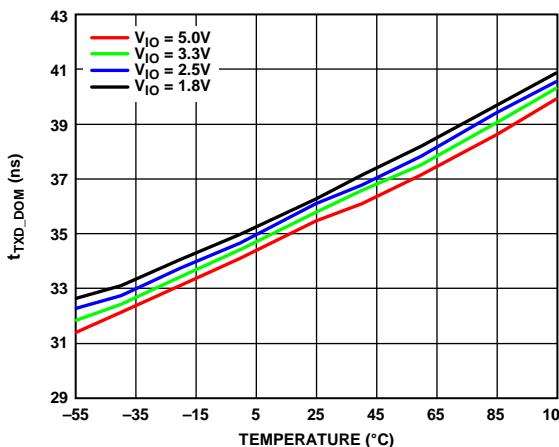


Figure 12. Receiver Input Hysteresis vs. Temperature

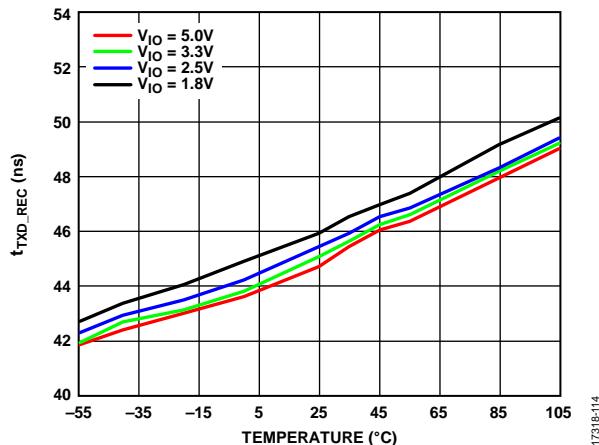
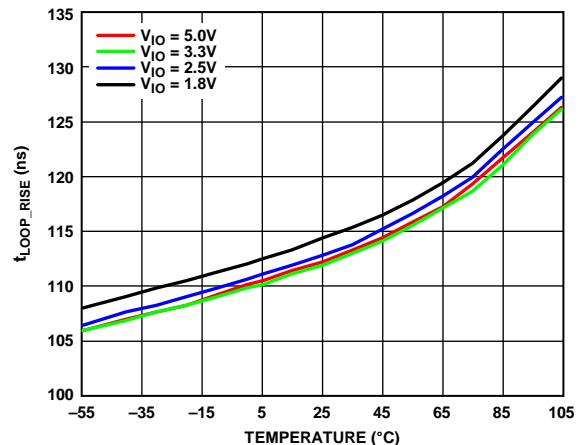
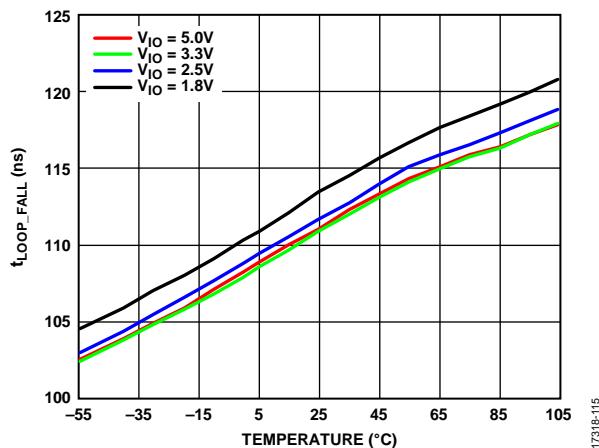
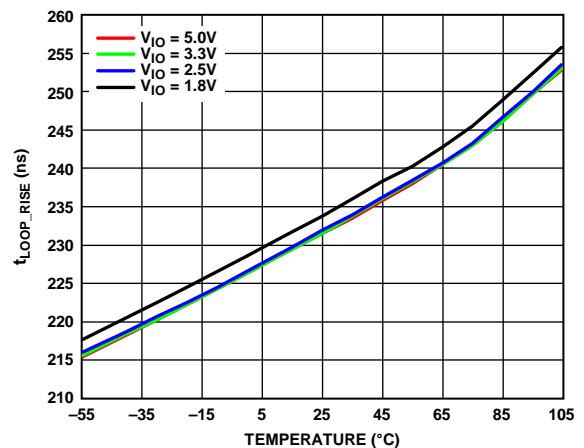
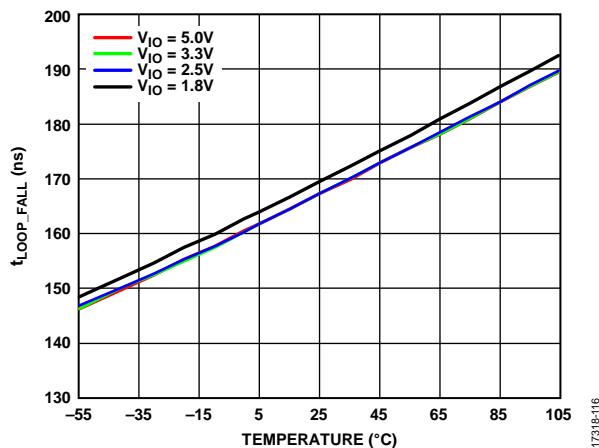
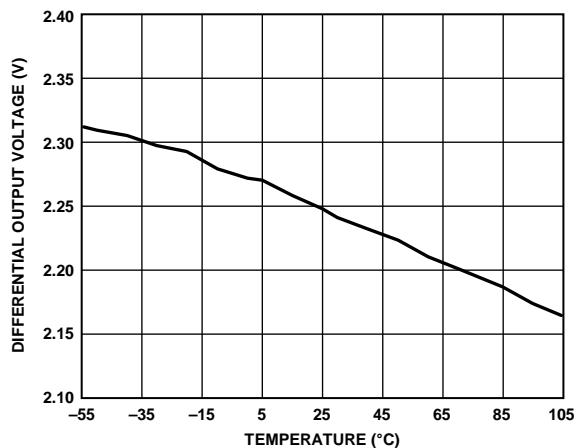
17318-112

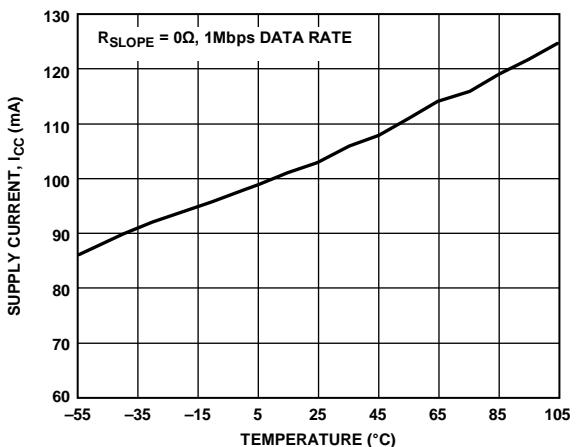
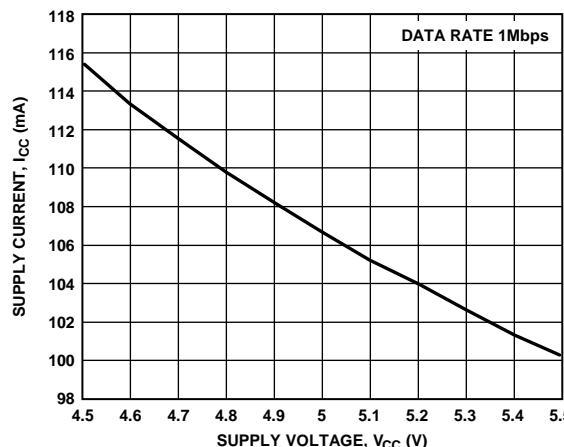
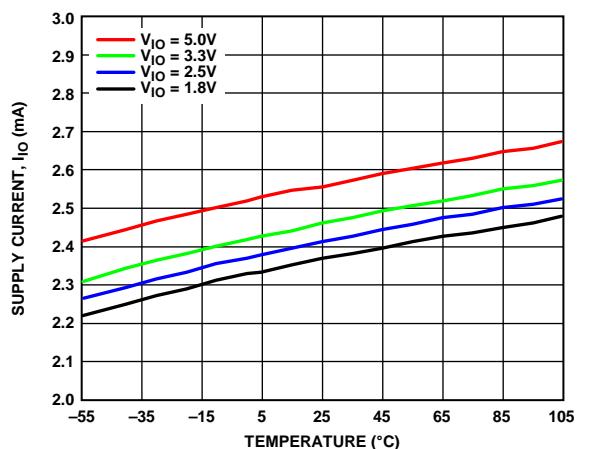
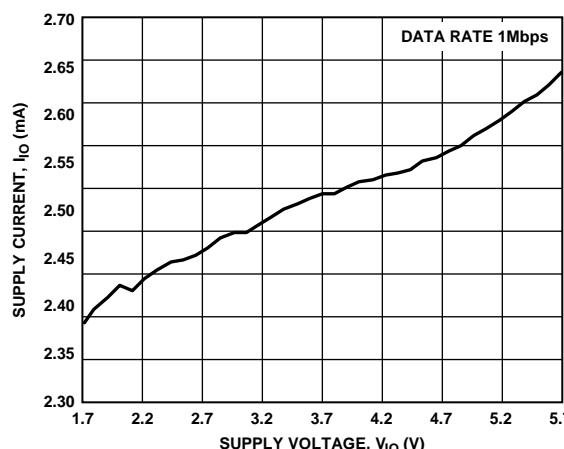
Figure 10. Supply Current, I_{IO} vs. Temperature (Inputs Idle)

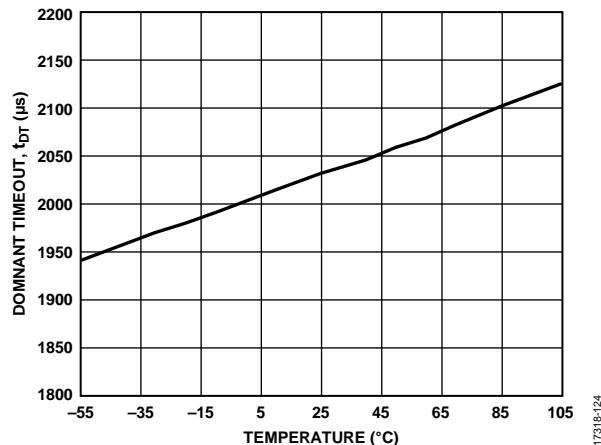
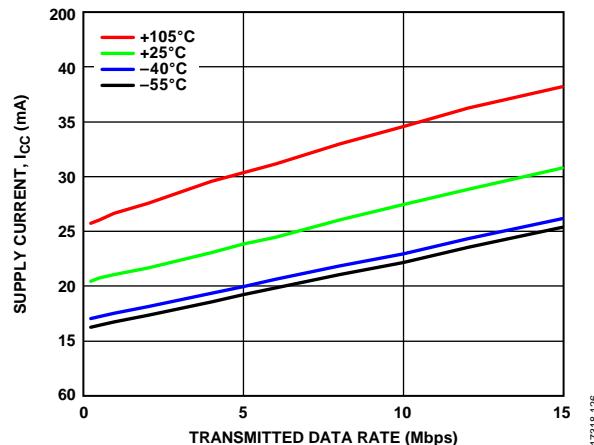
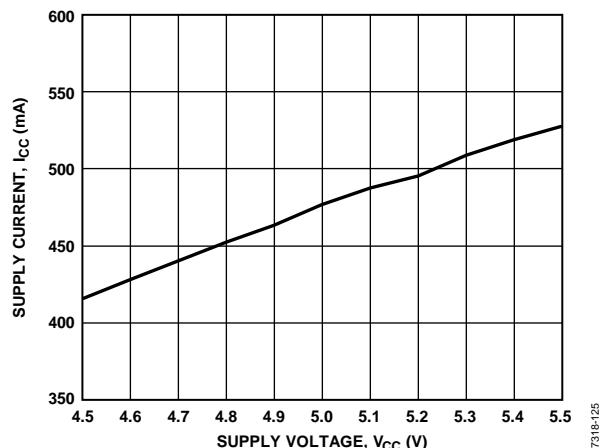
17318-110

Figure 13. t_{TXD_DOM} vs. Temperature

17318-113

Figure 14. t_{TXD_REC} vs. TemperatureFigure 17. t_{LOOP_RISE} vs. Temperature ($R_{SLOPE} = 0 \Omega$)Figure 15. t_{LOOP_FALL} vs. Temperature ($R_{SLOPE} = 0 \Omega$)Figure 18. t_{LOOP_RISE} vs. Temperature ($R_{SLOPE} = 47 k\Omega$)Figure 16. t_{LOOP_FALL} vs. Temperature ($R_{SLOPE} = 47 k\Omega$)Figure 19. Differential Output Voltage (V_{OD}) vs. Temperature

Figure 20. Supply Current, I_{CC} vs. TemperatureFigure 22. Supply Current, I_{CC} vs. Supply Voltage, V_{CC} , $RS = 0\Omega$, 1 MbpsFigure 21. Supply Current, I_{IO} vs. Temperature, $RS = 0\Omega$, 1 MbpsFigure 23. Supply Current, I_{IO} vs. Supply Voltage, V_{IO} , Data Rate = 1 Mbps

Figure 24. Dominant Timeout, t_{DT} vs. TemperatureFigure 26. Supply Current, I_{CC} vs. Transmitted Data RateFigure 25. Supply Current, I_{CC} vs. Supply Voltage, V_{CC}
(V_{ISOOUT} Shorted to GND_{ISO})

TEST CIRCUITS

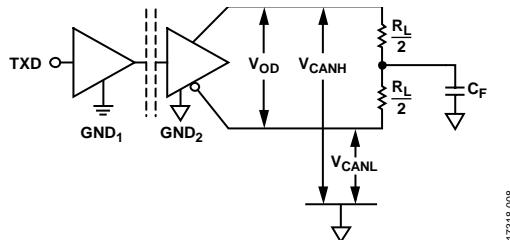


Figure 27. Driver Voltage Measurement

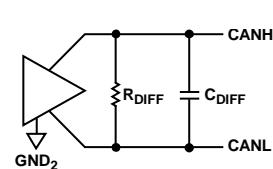
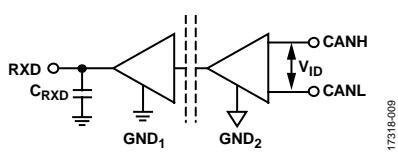
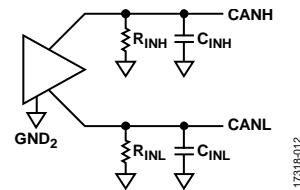
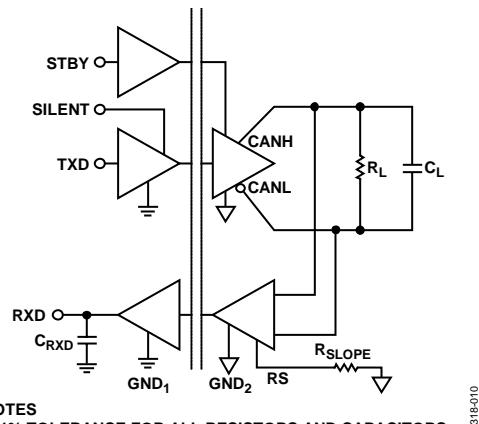
Figure 30. R_{DIFF} and C_{DIFF} Measured in Recessive State, Bus Disconnected

Figure 28. Receiver Voltage Measurement

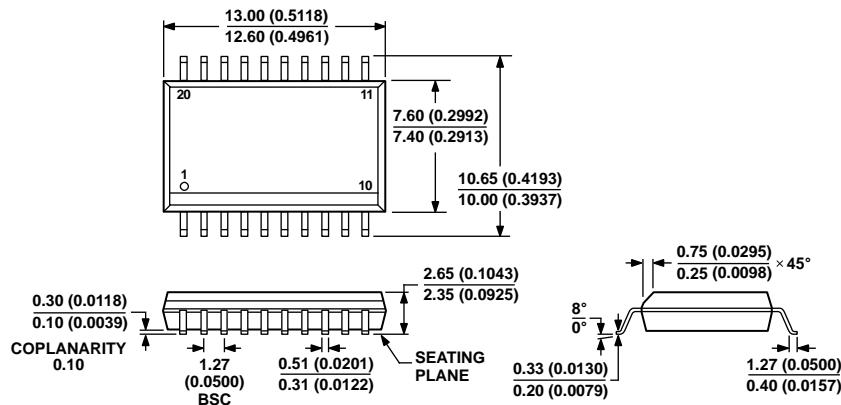
Figure 31. R_{INx} and C_{INx} Measured in Recessive State, Bus Disconnected

NOTES

1. 1% TOLERANCE FOR ALL RESISTORS AND CAPACITORS.

Figure 29. Switching Characteristics Measurements

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MS-013-AC
 CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
 (IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
 REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

06-07-2006-A

Figure 32. 20-Lead Standard Small Outline Package [SOIC_W]
 Wide Body
 (RW-20)
 Dimensions shown in millimeters and (inches)

ORDERING GUIDE

Model ^{1,2}	Temperature Range	Package Description	Package Option
ADM3057ETRWZ-EP	-55°C to +105°C	20-Lead Standard Small Outline Package [SOIC_W]	RW-20
ADM3057ETRWZ-EP-RL	-55°C to +105°C	20-Lead Standard Small Outline Package [SOIC_W]	RW-20
EVAL-ADM3055EEBZ		ADM3055E Evaluation Board	

¹ Z = RoHS Compliant Part.

² Use the [EVAL-ADM3055EEBZ](#) evaluation board to evaluate the ADM3057E-EP.